

ISSP2013 EXHIBIT

ISSP2013 Committee,
The Vacuum Society of Japan

The ISSP Panel Exhibit*) will be held in conjunction with The 12th International Symposium on Sputtering and Plasma Processes (ISSP2013) at the Kyoto Research Park from July 10 to 12, 2013. It will feature the broad spectrum of equipment, instruments, materials, systems, services, etc. for sputtering and plasma processes. At the last Exhibit, ISSP2011, 18 companies exhibited their offerings, and exchanged the information with about 300 attendees. This is the best opportunity for you to present, face-to-face, your products and services to a vital market. The Panel Exhibit will be opened parallel to ISSP2013 poster presentation at the same room. The ISSP2013 committee requests your company to attend this exhibition as an exhibitor. The up-to-date information can be seen at our web site: <http://issp2013.org/>. Please don't miss the terrific opportunity!

Your presentation at the technical session of the symposium is strongly recommended as well as the panel exhibit, which is expected to dramatically improve the impact of your company. (In this case, please apply as a normal presenting author.)

Exhibit Details

[Scope]

Process equipment (sputtering, evaporation, MBE, CVD, etching, etc.)

Analyzer, controller, and measurement apparatus

Related materials and components (Sputtering target, etc.)

[Location and term]

Kyoto Research Park, Kyoto, Japan

Exhibit: From 17:00 July 10 to 17:00 July 12, 2013 (Symposium: From 10:00 July 10 to 16:00 July 12)

(Closing time is tentative.)

[Exhibit fee]

¥ 120,000/unit (Japanese yen)

(Including the exhibit fee ¥100,000 and the registration fee ¥20,000)

[Special favor]

* The exhibitor can show one-page, monochrome advertisement on the programs (print media) and one-page, color advertisement on the proceedings (CD-ROM) for free. Please tolerate that the printing quality is not so high grade.

*We prepare a link to your home site on our web page, <http://issp2013.org/>, according to your request.

*In accordance with the request of exhibitor, an automatic CM slide presentation by Powerpoint (without sound, 30sec/company, no page limit) will be available during the break time of oral session. (Details will be informed later.)

[How to apply]

Please fill the application form (the last page) and send it to exhibit@issp2013.org by email.

Please attach the banner image file of your company, if you wish to make link point of your company's

*) Notice: ISSP2013 Exhibit is NOT the Manufacturer's Presentation which will be included in the technical program.

home page on the ISSP2013 web site.

Deadline: May 16, 2013

If you want to apply the one-page advertisement on the proceedings and on the programs, please send a PDF file (font embedding) to the committee office (see the end of this article).

[Policy]

*Description language is English.

*At least one person is required to explain the panels. He/she is entitled to attend all the session of ISSP2013 for free.

*For extra two persons of exhibitor, the registration fee is ¥20,000 per person. From the 4th person and up, please register as a normal participant.

*The carriage of all the exhibiting materials is to be made by yourself.

*Don't remove the panel before the closing of ISSP2013.

[Configuration]

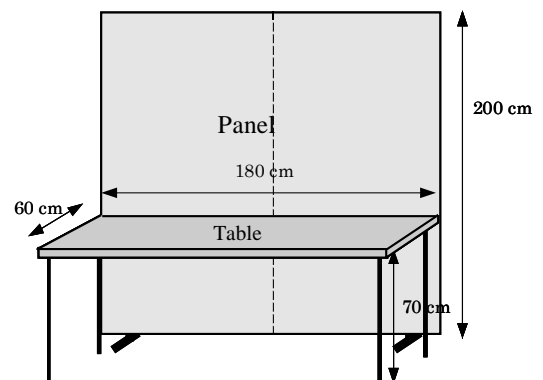
*One unit of exhibition space consists of a panel of about 180 cm (width) × 200 cm (height). and a desk of 180 cm (width) × 60 cm (depth) × 70 cm (height).

*The total weight of exhibiting materials on the desk should be less than 10 kg.

*If you need more space, you may use multiple exhibition units by paying additional fee. The acceptance will be informed later.

*Utilities of electrical power are available for personal computer use. It, however, is limited to 2 A (AC100 V).

*If you would like to make any special exhibition, please consult with us.



[Questions and Application]

ISSP2013 Office,

Advanced Material Science Center, Kanazawa Institute of Technology

3-1, Yatsukaho, Hakusan, Ishikawa 924-0838, JAPAN

TEL: +81-76-274-9250 FAX: +81-76-274-9251

E-mail: exhibit@issp2013.org

Exhibitors of the Past ISSP Exhibit

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| <ul style="list-style-type: none">• Advanced Energy Japan• AIMEC Corp.• ASTECH Corp.• BOC Coating Technology• Canon ANELVA Corp.• CSM Instruments SA• EIKO Corp. /EIKO Engineering Co., Ltd.• ENI JAPAN Ltd.• Fraunhofer-Institut für Elektronenstrahl- und Plasmatechnik• FTS Corp.• Fujikin Inc.• Gencoa Ltd.• Hakuto Co., Ltd.• HEMMI Slide Rule Co.,Ltd.• HITACHI ZOSEN Corp.• Hüttinger Elektronik GmbH• JAPAN ENERGY Corp.• J. A. Woollam Japan Corporation• JEOL Ltd.• KITANO SEIKI CO., LTD.• Kurt J. Lesker Company | <ul style="list-style-type: none">• Landmark Technology Corp.• MAKPLE Co. Ltd• MARUBUN Corp.• Matsubo Co., Ltd.• MITSUBISHI MATERIALS Corp.• Oerlikon Japan Co., Ltd.• NANO SCIENCE CORPORATION• NANOMETRICS JAPAN• NIHON VEECO K. K.• NIPPON MINING & METALS CO., LTD.• NOA SYSTEMS Inc.• NTT AFTY Corp.• OXFORD INSTRUMENTS• PEGASUS Software Inc.• SAES GETTERS JAPAN Co., Ltd.• Sanyu Electron Co., Ltd.• Science Technology Co., Ltd.• SHINCRON Co., Ltd.• SHOWA SHINKU Co., Ltd.• Singulus Technologies AG• Sputtered Films, Inc.• TDY INC. | <ul style="list-style-type: none">• Techscience Ltd.• THERMO RIKO CO., LTD.• ULVAC CRYOGENICS INC.• ULVAC JAPAN, Ltd.• ULVAC-PHI, INC.• UNIVERSAL SYSTEMS Co., Ltd.• VACUUM METALLUGICAL Co., Ltd.• VIC International Co., Ltd.• Von Ardenne Anlagentechnik GmbH• WaveFront Co., Ltd |
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ISSP2013

EXHIBIT APPLICATION FORM

Company Name			
Address			
Name of corresponding person Last name	PHONE	FAX. E-MAIL	
Middle name	FAX.		
First name	E-MAIL		
Application Date	Exhibit Fee per Unit ¥120,000		
AC100V-2A Power Supply (please check) <input type="checkbox"/> use <input type="checkbox"/> don't use	Number of Units for Exhibition (1unit=1panel and 1 table)		
Free advertisement page on the proceedings and on the programs <input type="checkbox"/> yes <input type="checkbox"/> no	_____ Units		
Link to your homepage from ISSP2013 website <input type="checkbox"/> yes <input type="checkbox"/> no	Total Fee ¥ _____		
Your URL _____ (Please attach your banner image file) CM presentation by Powerpoint automatic slide <input type="checkbox"/> yes <input type="checkbox"/> no			
Remarks			

Application dead line is May 16, 2013

Application form (only this page) is to be sent to the following address via Email.

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